



Collocatedwith



## The 5th JSME/ASME International Conference on Materials and Processing 2014

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ICM&P 2014 (JSME, The 22<sup>th</sup> Materials and ProcessingConference)
Organized by the Japan Society of Mechanical Engineers (JSME), the American Society of Mechanical Engineers (ASME), and the North American Manufacturing Research Institution of the Society of Manufacturing Engineers (NAMRI/SME)

# June 9 - 13, 2014Cobo Center, Detroit, Michigan USA

## — KEY SCHEDULE and DEADLINES

The 400-words abstract in English should be submitted to the conference website no later than December 1, 2013. Full paper due: January 1, 2014.

Acceptance notification: February 15, 2014 Final paper due: April 1, 2014,

Japanese Portal Site: http://www.jsme.or.jp/mpd/ICM&P2014/index\_jp.html Paper Submission and Registration Site: http://www.asmeconferences.org/ICMP2014/index.cfm

#### **ABOUT THE CONFERENCE**

In 2014, three leading international manufacturing and materials processing conferences – the 5th JSME/ASME International Conference on Materials and Processing (ICM&P) 2014 and the 9th ASME 2014 International Manufacturing Science and Engineering Conference (MSEC) and both co-sponsored by ASME and JSME, as well as the 42th NAMRC – An International Forum, sponsored by NAMRI/SME - will be collocated to better serve the needs of the manufacturing research community. The second-time collocated conference. The first-time was hosted by Oregon State University in 2011. In this time, these co-located conferences will be hosted by University of Michigan, at the Cobo Center, located on Detroit's revitalized riverfront, in conjunction with the SME Big M event and exhibition.

#### **PURPOSE& SCOPE**

Collaborated symposium of JSME, ASME, and NAMRI/SME in ICM&P2014 encourages the exploration of collaborative research and technology transfer and promotes professional networking. Papers reporting original and the latest basic and applied research in material and manufacturing processes and systems are sought. Research topics highlighted by ICM&P 2014 include, but are not limited to:

#### **TECHNICAL TRACKS**

#### **Track 1: Materials** 2-6: Forming and Joining of Traditional and Lightweight Materials(A2-5) Advances in Manufacturing and 1-1: Application of Metal Matrix 2-7: Surface Modification Technology Coating, Wear and Tribology (A2-12) Composites(A1-2) 2-8: Welding/Joining/Particle 1-2: Ceramics and Ceramic Matrix Deposition/Surface and Interface Composites A2-1: Laser, Process Innovations and Energy Field 1-3: Cutting-Edge Technologies and Manufacturing Methodology Innovation Around Soft Matter A2-2: Advances in Modeling, Analysis, and Simulation of 1-4: Design, Fabrication and Evaluation of Manufacturing Processes **Smart and Advanced Materials** Advances in Abrasive Machining Processes in honor A2-3: 1-5: Dynamic Behavior of Materials and of Professor Steve Malkin Structures Advances in Nontraditional Manufacturing A2-4: 1-6: Novel Porous Materials and their **Applications** A2-7: Advances in Manufacturing Processes of Biomedical Instruments 1-7: Polymer and Polymer Matrix Composites Advances in Experiments and Modeling of A2-9: Advancement in Manufacturing Processes for A1-1: Micromechanics and Microstructure Evolution in **Energy Efficiency** A2-10: Equipment and Tooling Design Innovations to Manufacturing Processes **Enhance Manufacturing Processe** Track 2: Processing Modeling, Monitoring and Control of Semiconductor A2-11: 2-1: Advanced Casting and Semisolid

#### Forming Techniques A2-13: 2-2: **Advanced Fabrication Process**

3-2:

2-5.	Advanced Fowder Frocessing reclinique	Track 3	s: Micro an
2-4:	Advances in Additive	3-1:	Creation an
	Manufacturing(A2-6)		Materials

#### Advances in Manufacturing Processes of 2-5: Biomedical Materials and Products(A2-8)

# Manufacturing Processes and Systems Advances in Processing of Polymer and Polymer-Based Composites **Micro and Nano Technologies** nd Applications of Micro-Nano

Micro/Nano Scale Fabrication

Processes(A3-1)

## Track 4: Properties, Applications and **Systems**

4-1:	Monitoring, Sensing, and Control for Intelligent Machining and Inspection(A4-9)
A4-1:	Advances in Concurrent Product Design and Manufacturing Systems
A4-2:	Advances in Manufacturing Systems Research for Energy Efficiency and Green Energy
A4-3:	Mechatronics for Advanced Manufacturing
A4-4:	Advances in Quality and Process Control in Manufacturing Systems
A4-5:	Challenges in Cloud Manufacturing
A4-6:	Optical Metrology and Imaging for Manufacturing Industry
A4-7:	System-level Integration of Additive Manufacturing for Design, Production and Supply Planning
A4-8:	Competitive Manufacturing Engineering
Track 5:	Sustainable Manufacturing

A5-1:	Sustainable Manufacturing for Emerging
	Technologies
A5-2:	Sustainable Industrial Systems

#### Advances in Manufacturing of Sustainable Composites

1-1: etc. JSME ICM&P Symposia 1-1: (A1-2)etc. Collocated Symposia A1-1:etc. ASME MSEC Symposia (You should submit paper from MSEC site)

#### **REGISTRATION FEE**

	~ April 8	April 9~
JSME/ASME member	\$650	\$750
Non-member	\$700	\$800
Student (JSME/ASME member)	\$350	\$450
Student (Non-member)	\$400	\$500

The registration fee includes admittance to all the conference events, a copy of the abstracts, a CD-ROM of proceedings coffee breaks, lunches, reception and banquet.

#### **PRESENTATIONS**

The presentations are basically planned to be oral. In the event of a large number of accepted papers, some will be assigned to poster sessions. This determination will be made by the Program Committee. Moreover, poster workshop for students is collaborated with Japan-US Advanced Collaborative Education Program (JUACEP: http://www.juacep.engg.nagoya-u.ac.jp/)

#### **SUBMISSION OF ABSTRACT**

Authors should submit a 400-words text abstract, no later than December 1, 2013, through the conference website including

- 1) Paper title, 2) Authors' names, 3) Affiliation,
- 4) Job title, 5) Mailing address, 6) Phone and fax, and
- 7) E-mail address.

(http://www.jsme.or.jp/mpd/ICM&P2014/index\_jp.html (in Japanese)

orhttp://www.asmeconferences.org/ICMP2014/index.cfm)

#### PREPARATION OF PROCEEDING PAPERS

The proceeding paper must be written in English. Length of the paper is more than 2 pages and no more than 10 pages (fully formatted, two-column, 8.5 x 11 in. pages). Details will be available on the conference website: http://www.asmeconferences.org/ICMP2014/index.cfm Authors should send their manuscript no later than the dead line in the conference website. Notification of acceptance will be given by February 15, 2014.

#### **PUBLICATION**

JSME is planning to publish a brand-new e-journal, Mechanical Engineering Journal. It will be commenced in February, 2014. Authors are encouraged to submit original papers to this journal. Their papers will be peer-reviewed again in accordance with the editorial policy. Authors who would like to submit to the transactions of ASME are also encouraged. Details will be available on the conference website.

#### **CONFERENCE COMMITTEE MEMBERS**

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#### **LOCATION AND SIGHT SEEING**

Detroit, a major metropolis in the US state of Michigan, has had a profound impact on the world. From the advent of the automotive assembly line to the Motown sound, modern techno and rock music, Detroit continues to shape both American and global culture. The city has seen many of its historic buildings renovated, and is bustling with new developments and attractions that complement its world class museums and theaters. Detroit is an exciting travel destination filled with technological advance and historic charm.